

Features:

- Isolated mounting base 3000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V _{RSM}	V _{RRM}	Type & Outline
2100V	2000V	MDx1000-20-411F3
2300V	2200V	MDx1000-22-411F3
2600V	2500V	MDx1000-25-411F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =60°C	150			1000	A
I _{F(RMS)}	RMS forward current		150			1570	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			50	mA
I _{FSM}	Surge forward current	10ms half sine wave V _R =0.6V _{RRM}	150			28	KA
I ² t	I ² T for fusing coordination					3920	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.82	V
r _F	Forward slop resistance					0.38	mΩ
V _{FM}	Peak forward voltage	I _{FM} =3000A	25			2.16	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.048	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	At 180° sine Single side cooled per chip				0.018	°C /W
V _{iso}	Isolation voltage	50Hz,R.M.S,t=1min, I _{iso} :1mA(max)		3000			V
F _m	Terminal connection torque(M12)					14.0	N·m
	Mounting torque(M8)					12.0	N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight					3460	g
Outline	411F3						

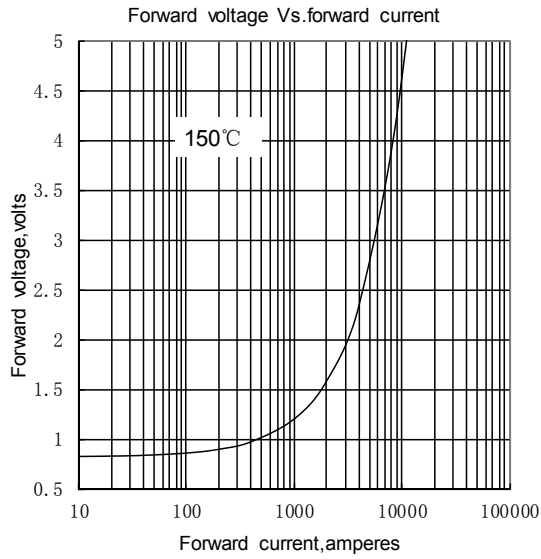


Fig.1

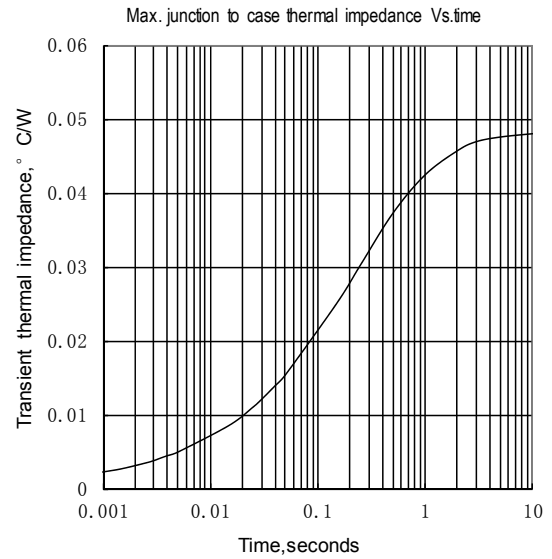


Fig.2

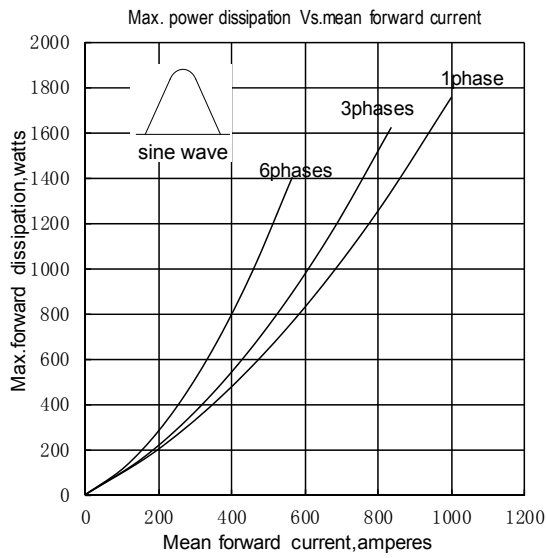


Fig.3

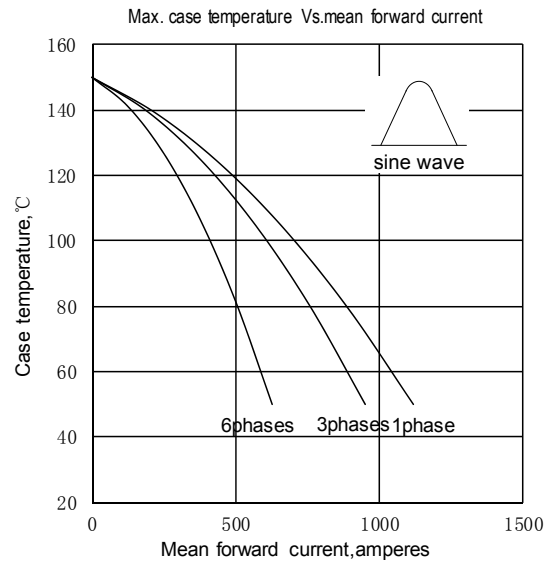


Fig.4

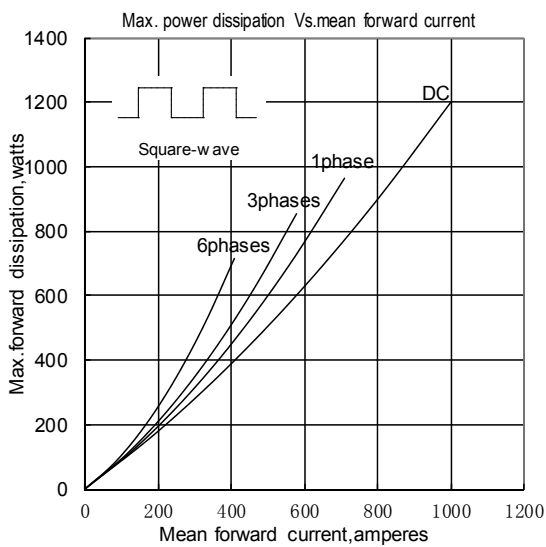


Fig.5

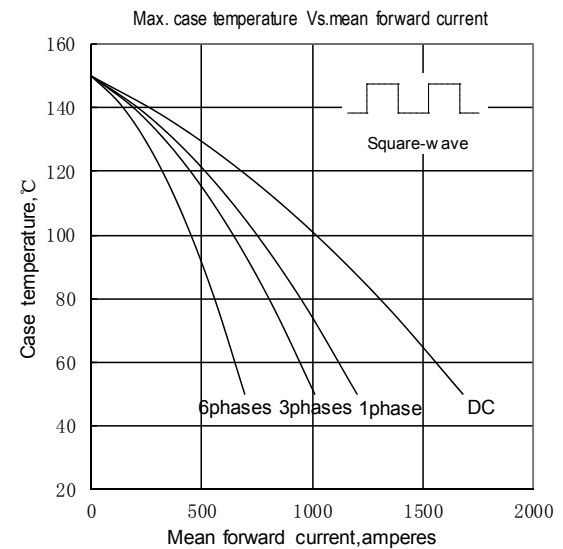


Fig.6

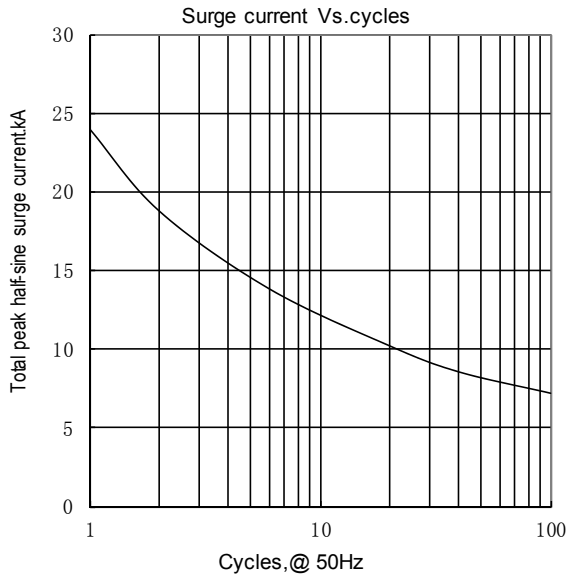


Fig.7

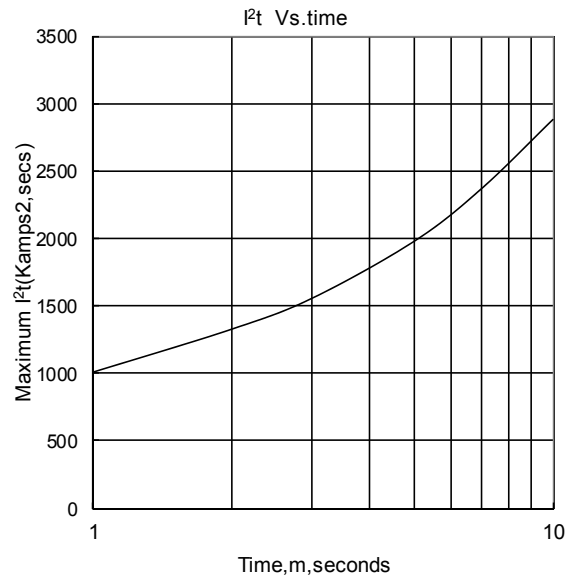
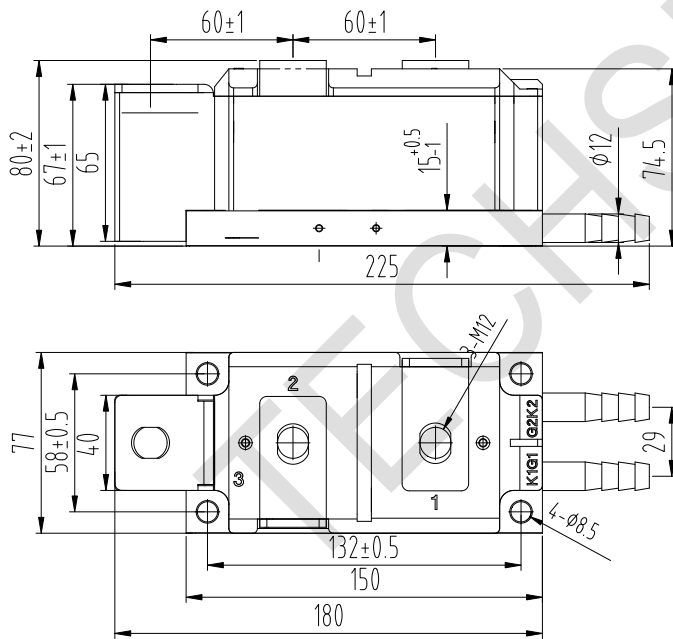
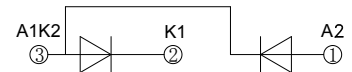


Fig.8

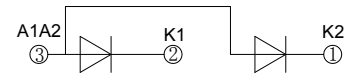
Outline:



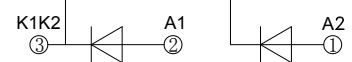
MDC



MDA



MDK



MD

